



Product Change Notification / ASER-05IJPW824

Date:

12-Feb-2021

Product Category:

Memory

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4556 Initial Notice: Qualification of SIGN as a new assembly site for selected SST39V320xx and SST38VF640xx device families available in 48L TSOP (12x20mm) package.

Affected CPNs:

[ASER-05IJPW824_Affected_CPN_02122021.pdf](#)

[ASER-05IJPW824_Affected_CPN_02122021.csv](#)

Notification Text:

PCN Status:Initial notification.

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the icons found in the Affected CPNs section to the right.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .csv).

Description of Change:Qualification of SIGN as a new assembly site for selected SST39V320xx and SST38VF640xx device families available in 48L TSOP (12x20mm) package.

Pre Change:

Assembled at LPI assembly site.

Post Change:

Assembled at SIGN assembly site.

Pre and Post Change Summary:

	Pre Change		Post Change
Assembly Site	Lingsen Precision Industries, LTD. (LPI)		Signetics Corporation (SIGN)
Wire material	Au		Au
Die attach material	8340		8340
Molding compound material	G700		G700
Lead frame material	C7025		C7025
	See Pre and Post Change comparison attachment.		
Lead frame paddle size	207 x 142 mils	183x161 mils	209x165 mils
DAP surface prep	Ring Plating	Double Ring Plating	Double Ring Plating

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve manufacturability by qualifying SIGN as a new assembly site.

Change Implementation Status:In Progress

Estimated Qualification Completion Date:August 2021

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	February 2021				-->	August 2021				
	6	7	8	9		3	3	3	3	3
Workweek						2	3	4	5	6
Initial PCN Issue Date		X								
Qual Report Availability										X
Final PCN Issue Date										X

Method to Identify Change:Traceability code

Qualification Plan:Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:February 12, 2020: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content

of the applicable products.

Attachments:

[PCN_ASER-05IJPW824 Qual Plan.pdf](#)

[PCN_ASER-05IJPW824_Pre and Post Change Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

SST39VF3201C-70-4I-EKE
SST39VF3202C-70-4I-EKE
SST39VF3201C-70-4I-EKE-REL
SST39VF3201C-70-4I-EKE-T
SST39VF3202C-70-4I-EKE-T
SST38VF6401B-70I/TV-100
SST38VF6401B-70I/TV-101
SST38VF6401B-70I/TV
SST38VF6402B-70I/TV
SST38VF6403B-70I/TV
SST38VF6404B-70I/TV
SST38VF6401BT-70I/TV
SST38VF6402BT-70I/TV
SST38VF6403BT-70I/TV
SST38VF6404BT-70I/TV



MICROCHIP

QUALIFICATION PLAN SUMMARY

PCN#: ASER-05IJPW824

**Date:
Feb 04, 2021**

**Qualification of SIGN as a new assembly site for selected
SST39V320xx and SST38VF640xx device families
available in 48L TSOP (12x20mm) package.**

Purpose: Qualification of SIGN as a new assembly site for selected SST39V320xx and SST38VF640xx device families available in 48L TSOP (12x20mm) package.

<u>Misc.</u>	Assembly site	SIGN
	BD Number	BFL-00001
	MP Code (MPC)	S00017W9XM70
	Part Number (CPN)	SST39VF3201C-70-4I-EKE
	MSL information	MSL 3 / 260
	Assembly Shipping Media (T/R, Tube/Tray)	Tray
	Base Quantity Multiple (BQM)	96
	Reliability Site	MTAI
	CCB No	4556
<u>Lead-Frame</u>	Paddle size	209x165
	Material	C7025
	DAP Surface Prep	Double Ring Plating
	Treatment	Roughened
	Process	Stamped
	Lead-lock (With Locking Holes)	No
	Part Number	FLF-00001
	Lead Plating	Matte Sn
	Strip Size	211X60mm
	Strip Density	24 units/strip
<u>Bond Wire</u>	Material	Au
<u>Die Attach</u>	Part Number	8340A
	Conductive	Yes
<u>MC</u>	Part Number	G700
<u>PKG</u>	PKG Type	TSOP
	Pin/Ball Count	48L
	PKG width/size	12x20mm

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Pkg. Type	Special Instructions
Standard Pb-free Solderability	J-STD-002D ; Perform 8 hour steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Standard Pb-free: Matte tin/ NiPdAu finish, SAC solder, wetting temp 245°C for both SMD & through hole packages.	22	5	1	27	> 95% lead coverage	5	TSOP 48L	Standard Pb-free solderability is the requirement. SnPb solderability (backward solderability- SMD reflow soldering) is required for any plating related changes and highly recommended for other package BOM changes.
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0	5	TSOP 48L	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5	0	5	TSOP 48L	30 bonds from a min. 5 devices.
Physical Dimensions	Measure per JESD22 B100 and B108	10	0	3	30	0	5	TSOP 48L	
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	TSOP 48L	
HTSL (High Temp Storage Life)	+175 C for 504 hours or 150°C for 1008 hrs.	45	5	1	50	0	10	TSOP 48L	
Preconditioning - Required for surface mount devices	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; MSL3 / 260c	231	15	3	738	0	15	TSOP 48L	Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test.
HAST	+130°C/85% RH for 96 hours or 110°C/85%RH for 264 hours.	77	5	3	246	0	10	TSOP 48L	Spares should be properly identified.
UHAST	+130°C/85% RH for 96 hrs or +110°C/85% RH for 264 hrs.	77	5	3	246	0	10	TSOP 48L	Spares should be properly identified.
Temp Cycle	-65°C to +150°C for 500 cycles.	77	5	3	246	0	15	TSOP 48L	Spares should be properly identified.

CCB 4556
Pre and Post Change Summary
PCN #: ASER-05IJPW824



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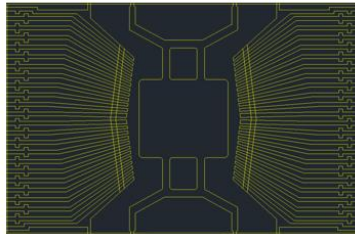
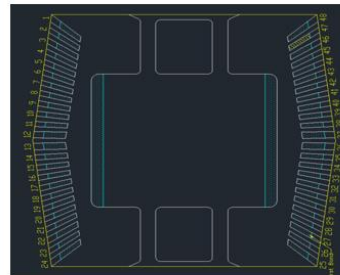
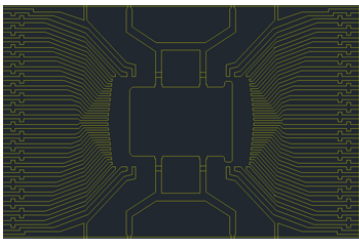
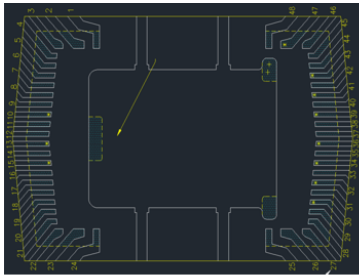


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package.**

Lead frame Comparison

LPI



SIGN

